

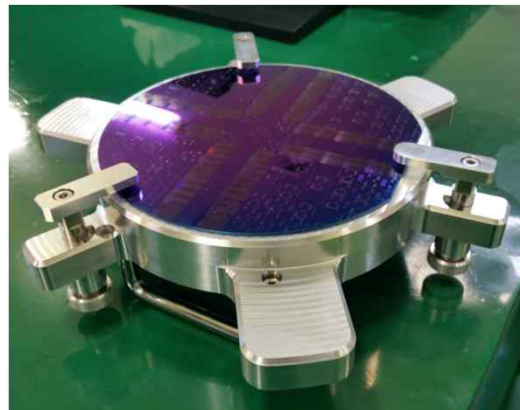
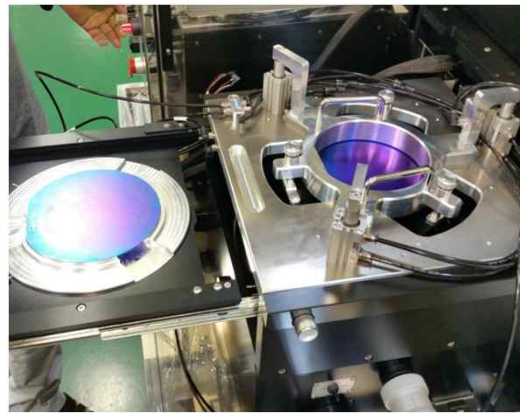
The Development and the commercialization of the Mask Aligner for wafer
Midas System will continue to grow along with the value creation for our customers.

<http://www.aligner.co.kr>

MIDAS Bond aligner kit



The MIDAS Bond aligner is good for research and variable process of all applications. It represents next generation of full-field systems.



ITEM	SPECIFICATIONS
Substrate Size	6" wafer
Alignment accuracy	1um
Bonding methods	Direct/fusion
Alignment methods	Top and Bottom side
Dimension(mm)	350×350×265(Bond kit only)



589.Yongsan-dong, Yuseong-gu, Daejeon, 305-500, Korea
Tel : +82-42-936-7620 / Fax : +82-42-936-7623 / A/S Center : +82-1544-7618
Homepage : www.aligner.co.kr / www.midas-system.com